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## ABSTRACT

A method for the fabrication of a double-sided electrical interconnection flexible circuit (200) particularly useful as a substrate for an area array integrated circuit package. A copper matrix with studs (203) is pressed through a dielectric film (201) having a copper layer on the opposite surface, thereby forming an intermediate structure for a flex circuit with self-aligned solid copper vias in a one step process. The contacts are reinforced by plating both surfaces with a layer of copper, and conventional processes are used to complete the circuit patterning.

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